- 3. (Once amended) The composition of claim 2 in which the composition comprises from about 10 percent by weight to about 80 percent by weight of water.
- 4. (Once amended) The composition of claim 3 in which the composition comprises from about 20 percent by weight to about 80 percent by weight of organic solvent.

Claims 1-2, and 5-9 stand as amended through Preliminary Amendment on December 4th 2001.

Please add the following new claims:



- 32 10 (new). A composition for the removal of etch residues from integrated circuits using copper materials, in which the composition comprises from greater than 20% to about 50% by weight choline, water, and an organic solvent.
- 33 1 (new). The composition of claim 10 in which the composition comprises from about 10 percent by weight to about 80 percent by weight of water.
- 34 12 (new). The composition of claim 11 in which the composition comprises from about 20 percent by weight to about 80 percent by weight of organic solvent.
- The composition of claim 10 in which the choline compound comprises choline hydroxide, choline bicarbonate or choline chloride.
- 34 (new). The composition of claim 13 in which the choline compound comprises choline hydroxide.
- The composition of claim 13 in which the organic solvent comprises propylene glycol, dimethyl sulfoxide, monoethanolamine, or diglycolamine.
- 7° 16 (new). The composition of claim 10 in which the composition additionally comprises hydroxylamine or hydroxylamine salt.
- The composition of claim 10 in which the composition additionally comprises a corrosion inhibitor.

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- (new). A composition for the removal of etch residues from integrated circuits using copper materials, in which the composition comprises from about 10% by weight choline to about 50% by weight choline, water, and a glycol selected from the group consisting of ethylene glycol, ethylene glycol alkyl ether, diethylene glycol alkyl ether, triethylene glycol alkyl ether, propylene glycol, and propylene glycol alkyl ether.
- (new). The composition of claim 18 where the choline comprises choline hydroxide and the glycol comprises propylene glycol.
- The composition of claim 19 in which the composition comprises about 22.5% by weight choline hydroxide, about 50% by propylene glycol, and about 27.5% by weight water.
- The composition of claim 12 in which the composition additionally comprises from about 2 to about 12% by weight of hydroxylamine or hydroxylamine salt.
- 44 22 (new). F The composition of claim 21 in which the composition additionally comprises from about 0.5 to about 5% by weight of a corrosion inhibitor.
- 15 23 (new). The composition of claim 4 in which the choline is choline hydroxide and the organic solvent is propylene glycol.

REMARKS

Claims 1-23 will be pending and under consideration upon entry of this amendment.

Claims 10-23 have been added to more particularly point out and distinctly claim the invention. Support for these claims is set forth in the following table:

<u>Claim</u>	Example of support in the specification
10	page 4, paragraph [0057] ¹
11	page 4, paragraph [0057]
12	page 4, paragraph [0057]
13	page 3, paragraph [0050]
14	page 3, paragraph [0050]

¹ References are made to the published application No. US 2002/0134963 A1.